

Application Note: SY67134

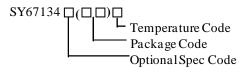
Medium Voltage H-Bridge IC

General Description

The SY67134 is a H-bridge motor driver solution for motion-control applications. The highly integrated Hbridge driver block consists of two half-bridges with internal logic control, gate drive, over current protection and charge pump circuit.

The SY67134 operates with a power-supply voltage range from 5V to 40V, and 3.6A maximum output current. To be compatible with industry-standard devices, the SY67134 uses the PWM input interface. The SY67134 also provides over current protection, under voltage lockout and thermal shutdown protection. The device is packaged in SO8E.

Ordering Information



Ordering Number	Package type	Note
SV6713/JECC	SOSE	

Features

- Power Supply Voltage Range from 5V to 40V
- 3.6A Maximum Drive Current
- H-bridge Motor Driver
- **PWM** Interface
- Low Power Standby Mode with Less than 15 µA Supply Current
- Internal Over Current Protection, Under Voltage Lockout and Thermal Shutdown
- Automatic Fault Recovery
- Synchronous Rectification
- Compact Package: SO8E

Applications

- Consumer Products
- Robotics

Typical Application

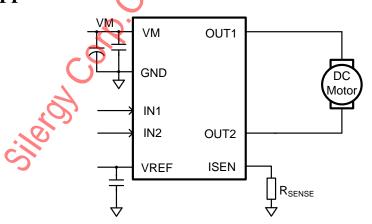
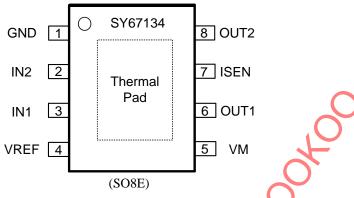


Figure 1. Typical Application Circuit



Pin out (Top View)



Top Mark: CFXxyz (device code: CFX, x=year code, y=week code, z=lot number code)

Name	Number	Description
GND	1	Ground pin.
IN2	2	Logic input 2 pin. Logic high set OUT2 High, this pin has an internal pull-down resistor.
IN1	3	Logic input 1 pin. Logic high set OUT1 High, this pin has an internal pull-down resistor.
VREF	4	Current regulator voltage reference. I _{CHOP} =VREF/10/R _{SENSE} . Decouple this pin to GND with at least 0.1 uF ceramic capacitor.
VM	5	Power supply pin. Decouple this pin to GND with 10uF ceramic cap and sufficient electronic capacitor.
OUT1	6	Output 1 pin. Connect this pin to motor winding.
ISEN	7	Current sense resistor connection pin.
OUT2	8	Output 2 pin. Connect this pin to motor winding.
Thermal Pad	-	Exposed pad for enhanced thermal dissipation. Connect to ground for maximum thermal efficiency.

Block Diagram

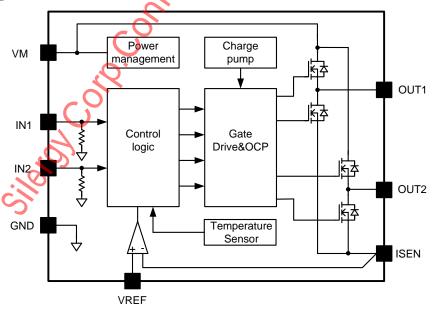


Figure 2. Block Diagram



Absolute Maximum	Ratings (Note 1)

VM, OUT1, OUT2	-0.3V to 40V
IN1, IN2	-0.3V to 6V
VREF	-0.3V to 4V
ISEN	
Junction Temperature (T _J)	
Storage Temperature	
Package Thermal Resistance	
θ_{JA} (Note 2)	62 ℃/W
θ_{JC} (Note 2)	20 ℃/W

Recommended Operating Conditions

VM, OUT1, OUT2		5V to 32V
IN1, IN2		0V to 5V
VREF		0V to 3.3V
ISEN		0.3V to 0.3V
R _{SENSE}	······	less than $100 \text{m}\Omega$
Logic Input PWM Frequency		0Hz to 100 kHz
H-Bridge Output Current (Note3)		0 to 3.6A
Junction Temperature Range		40 ℃ to 125 ℃
Ambient Temperature Range	<u>4</u> V	
r		0 0 00 0



Electrical Characteristics

 $(T_A = 25 \text{ C}, V_M = 24 \text{V}, \text{ unless otherwise specified})$

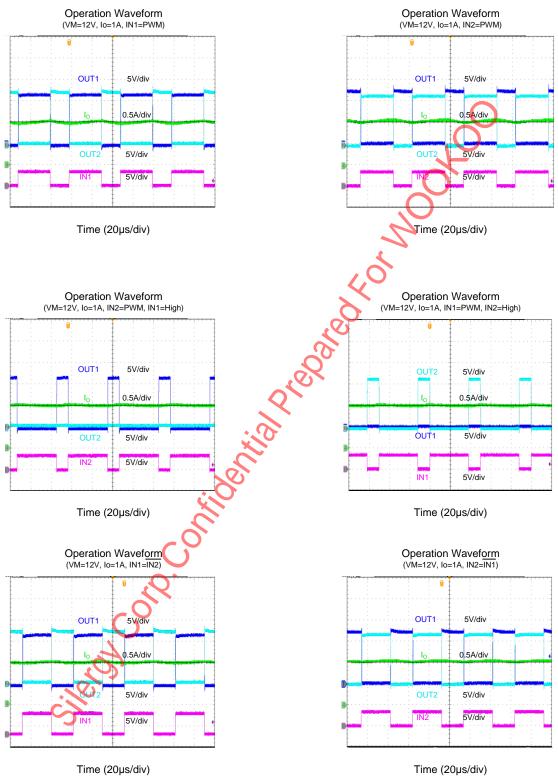
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Power Supply						
Supply Voltage Range	$V_{\rm M}$		5		32	V
Under Voltage Threshold	V_{UVLO_TH}	V _M Rising		4.7	5	V
Under Voltage Hysteresis	V _{UVLO_HYS}			200		mV
VM Operating Supply		Low power standby mode			15	μΑ
Current	I_{IN}	<30kHz PWM, OUTx float			3	mA
Logic Level Input				1		
Input Low Voltage	V_{IL}		4	J	0.5	V
Input High Voltage	V_{IH}		1.5			V
Input Low Current	$I_{ m IL}$	V _{INX} =0V	-1	0	1	μΑ
Input High Current	I_{IH}	$V_{INX} = 3.3V$	20	50	100	μΑ
H-Bridge MOSFETs		•				
HS + LS MOSFETs on	R_{dson}		7		500	$\mathrm{m}\Omega$
Resistance					300	1115.2
Off-State Leakage Current	I_{OFF}	, 0			±500	nA
Dead time	T_{D}	(Note 4)			500	ns
Current Regulation						
Current Regulation Reference	V_{REF}	Use external voltage as VREF	0.1		3	V
Voltage	▼ REF	Ose external voltage as VICLI			3	•
Current Gain	A_{V}	VREF/I _{CHOP} , VREF=2V	9.5		10.5	V/V
Blank Time	T _{BLANK}	2	1	2	3	μs
Constant Off-time	T_{OFF}	(0)	12	24	35	μs
Timing		<u>Q</u>				
Time to Standby Mode	T_{ESTB}	IN1=IN2< V _{IL} , (Note 4)		1		ms
Protection						
Output Over Current Limit	I_{OCP}		3.65	4.5	5.5	A
OCP Regulate Time	t_{REG}	(Note 4)		1.5		μs
OCP Retry Time	t _{RTY}	(Note 4)		3		ms
Thermal Shutdown	T_{SD}	(Note 4)		165		\mathcal{C}
Temperature						
Thermal Shutdown Hysteresis	T_{HYS}	(Note 4)		30		\mathcal{C}

Note 1: Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

- **Note 2**: θ_{JA} is measured in the natural convection at $T_A = 25 \, \text{C}$ on a two-layer SILERGY Evaluation Board.
- **Note 3**: Power dissipation and thermal limits must be observed.
- Note 4: This spec does not test, and it is guaranteed by design.



Typical Performance Characteristics





Functional Description

H-Bridge Control

The bridge is controlled by a PWM input interface, and the following table shows the control logic of the device:

T-1-	1 - 1	ו ח	P4	1. 7	r_1_	1.
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IN1	IN2	OUT1	OUT2	Function (DC Motor)
0	0	Z	Z	Coast
0	1	L	Н	Reverse
1	0	Н	L	Forward
1	1	L	L	Brake

Standby Mode

Low power standby mode will be active when both input IN1 and IN2 pin voltage are logic low for longer than 1ms. Standby Mode disables most of the internal circuitry, including the charge pump and the regulator. Any PWM commands are issued to the device, before the IC comes out of standby mode, the charge pump should be allowed to reach its regulated voltage (a maximum delay of 200us).

Current Regulation

When voltage of the current sense resistor is equals to the comparator (rip) value, the IC will enter into mix decay mode. The IC decays the current at fixed off time of 24us. The PWM thopping current is set by a comparator which compares the voltage across a current sense resistor connected to the ISEN pin with a reference voltage.

The chopping current is calculated in Equation 1.

$$I_{CHOP} = \frac{VREF}{10 \times R_{SENSE}} \tag{1}$$

Example:

If a 0.05Ω sense resistor is used, and VREF=1V, the chopping current will be $1V/10/0.05 \Omega = 2A$.

Once the chopping current threshold is reached, the H-bridge will switch to decay mode. At the beginning of decay, the motor runs at fast decay, then the motor runs at slow decay.

Note that if current control is not needed, the ISEN pin should be connected to ground directly.

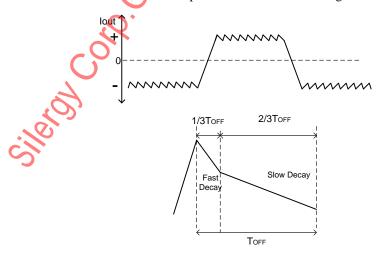


Figure 3. Current Regulation and Decay timing



Synchronous Rectification

When the current regulation is triggered, load current will recirculate. The IC turn on the MOSFETs, and short the body diode. This helps to lower the power disspation. When a zero current is detected, the synchronous rectification will be turn off to prevent reversal of the load current.

Protection Circuits

The device is fully protected against under voltage, over current and thermal shutdown.

Over Current Protection (OCP)

An analog current limit circuit on each FET limits the current through the FET. If this analog current limit persists for longer than the OCP regulation time, all FETs in the H-bridge will be disabled. The driver will be re-enabled after the OCP retry period (t_{RTY}) passed. If the fault condition is still present, the cycle will repeat. If the fault is no longer present, normal operation will resume.



Figure 4. OCP schematic

Under Voltage Lockout (UVLO)

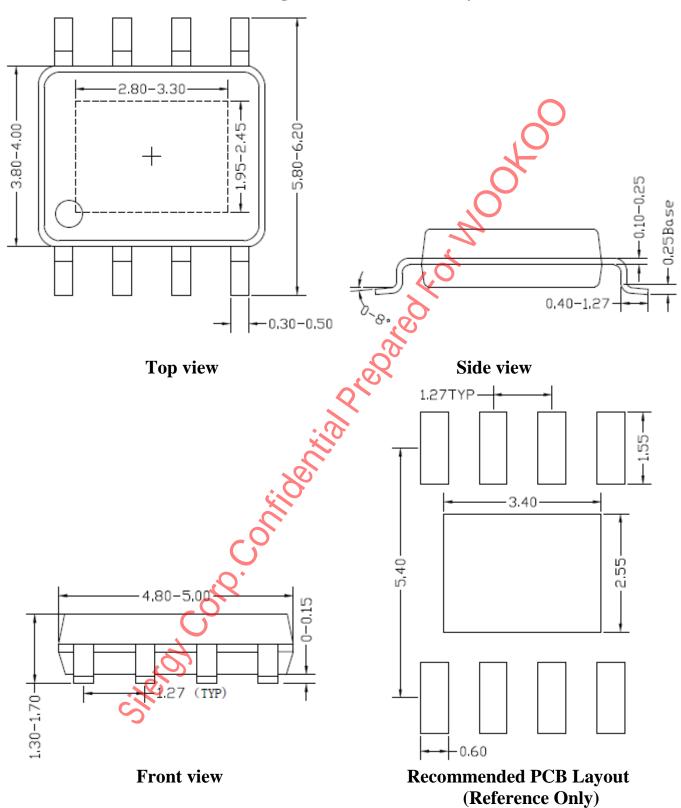
If at any time the voltage on the VM pin falls below the under voltage lockout threshold voltage, all circuitry in the device will be disabled and internal logic will be reset. Operation will resume when VM rises above the UVLO threshold.

Thermal Shutdown Protection (TSD)

The device has thermal shutdown as described in the Protection Circuits section. If the die temperature exceeds approximately 165 °C, the device will be disabled until the temperature drops to a safe level. Any tendency of the device to enter thermal shutdown is an indication of either excessive power dissipation, insufficient heatsinking, or a too high ambient temperature.



SO8E Package Outline & PCB layout



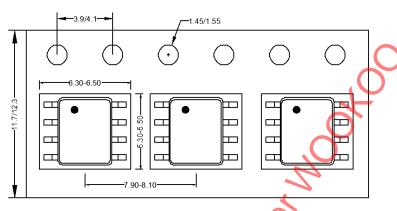
Notes: All dimension in millimeter and exclude mold flash & metal burr.



Taping & Reel Specification

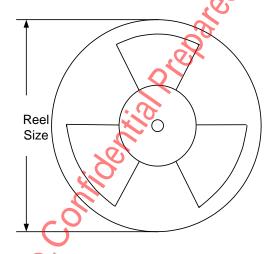
1. Taping orientation

SO8E



Feeding direction ——

2. Carrier Tape & Reel specification for packages



Package types	Tape width	Pocket	Reel size	Trailer *	Leader *	Qty per reel
i dekage types	(mm)	pitch(mm)	(Inch)	length(mm)	length (mm)	(pcs)
SO8E	12	8	13"	400	400	2500

3. Others: NA



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10